

REMARKS

Applicant respectfully requests reconsideration and allowance of claims 6-7, 12-14, and 19-21, which are pending in the above-identified application. Claims 6-7, 12-14, and 19-21 have been rejected. Applicant has amended claim 6 herein. No new matter is added by the amendment herein. Support for the amendments is found in FIGS. 1-3 and paragraphs [0041-0043] of the specification of the instant application as originally filed.

Allowable Claims

Applicant acknowledges with appreciation that at page 3 of the Office Action, the Examiner deemed claims 6-7, 12-14, and 19-21 as containing patentable matter, subject to a rejection under 35 U.S.C. §112, first paragraph.

Objection to the Drawing

At page 2 of the Office Action, the Examiner objected to the drawings alleging that they do not show the "hollow part" which does not overlap the integrated circuit. Applicant traverses this objection.

As illustrated in FIG. 3, and described at [0042] of the instant specification, the coolant passage 70 is the hollow part of the transparent cooling mechanism 20. FIG. 3 illustrates that the portion of the integrated circuit 16 that is subject to observation by the image sensor 24 is not overlapped by the passage 70. The conclusion that the passage carrying coolant through the cooling mechanism 20 is covered by the claimed "hollow part" is consistent with other portions of the specification as well. In view of the above, Applicant respectfully requests withdrawal of the drawing objection.

Claim Rejections Under §112– Written Description Rejection

At pages 2-3 of the Office Action, the Examiner rejected claims 6-7, 12-14, and 19-21 under 35 U.S.C. §112, first paragraph, as failing to comply with the written description requirement. The

Examiner takes the position that the specification [0043] permits the claimed "hollow portion" to overlies some portions of the die 16 (and thus be interposed between the die 16 and the camera 24), but not others. The Examiner takes the position that the language of claim 6, however, requires that the "hollow portion" cannot overlies any portion of the die 16.

In response, Applicant has amended claim 6 to require that "the hollow part is provided so as not to overlap at least a portion of the semiconductor integrated circuit subject to observation by the image capturing sensor." This language is consistent with FIG. 3 and paragraphs [0041] - [0043] of the specification, which make clear that at least one embodiment permits some portion of the die 16 to be overlapped by the hollow part, so long as the part of the die 16 subject to observation by the camera 24 is not obstructed.

Accordingly, Applicant respectfully requests that the §112, first paragraph, rejection of the subject claims be withdrawn.

Conclusion

In view of the foregoing, Applicant submits that the instant claims are in condition for allowance. Early and favorable action is earnestly solicited. In the event there are any further fees due and owing or refundable in connection with this matter, please charge/credit same to our Deposit Account No. 11-0223.

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Respectfully submitted,

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